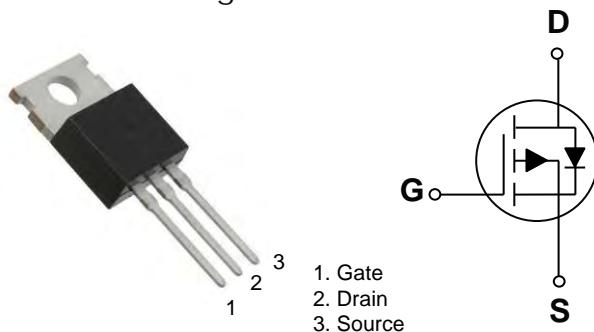


-100V P-Channel MOSFETs

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO-220 Pin Configuration



BVDSS	RDS(ON)	ID
-100V	95mΩ	-24A

Features

- -100V,-25A, RDS(ON) =95mΩ @VGS = -10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 25	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-24	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	-15.1	A
I_{DM}	Drain Current – Pulsed ¹	-96	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	125	W
	Power Dissipation – Derate above 25°C	1	W/°C
T_{STG}	Storage Temperature Range	-50 to 150	°C
T_J	Operating Junction Temperature Range	-50 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.0	°C/W



-100V P-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	0.06	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-100\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=-80\text{V}$, $V_{GS}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 25\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-6\text{A}$	---	75	95	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-3\text{A}$	---	80	110	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = -250\mu\text{A}$	-1.2	-1.6	-2.2	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-4.46	---	$\text{mV}/^\circ\text{C}$

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{DS}=-50\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-5\text{A}$	---	40.4	70	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	7.7	15	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	6.6	13	
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=-30\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=-1\text{A}$	---	27	54	ns
T_r	Rise Time ^{2,3}		---	12	24	
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	150	300	
T_f	Fall Time ^{2,3}		---	45	90	
C_{iss}	Input Capacitance	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	2250	3900	pF
C_{oss}	Output Capacitance		---	130	250	
C_{rss}	Reverse Transfer Capacitance		---	90	180	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	10		Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-24	A
I_{SM}	Pulsed Source Current		---	---	-48	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time ²	$I_s=-1\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	---	---	ns
Q_{rr}	Reverse Recovery Charge ²		---	---	---	nC

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

-100V P-Channel MOSFETs

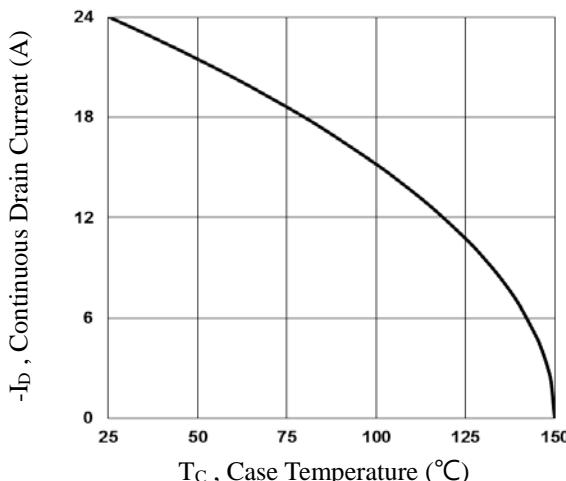


Fig.1 Continuous Drain Current vs. T_C

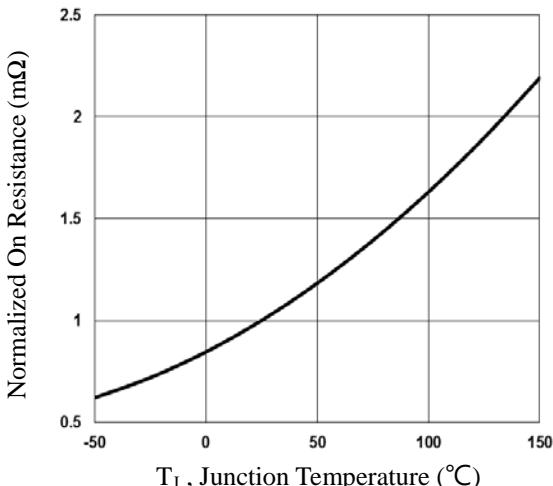


Fig.2 Normalized RDS(on) vs. T_J

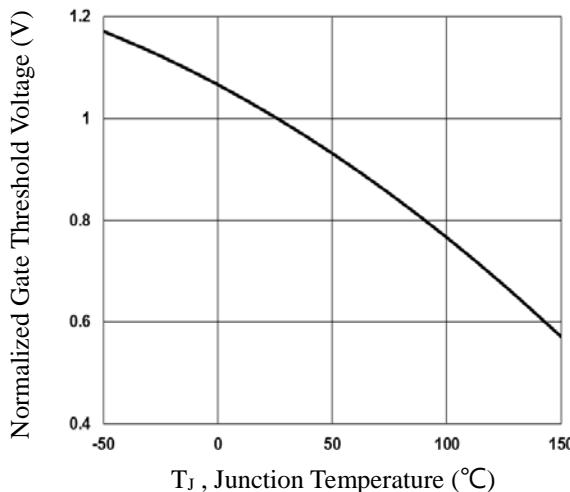


Fig.3 Normalized V_{th} vs. T_J

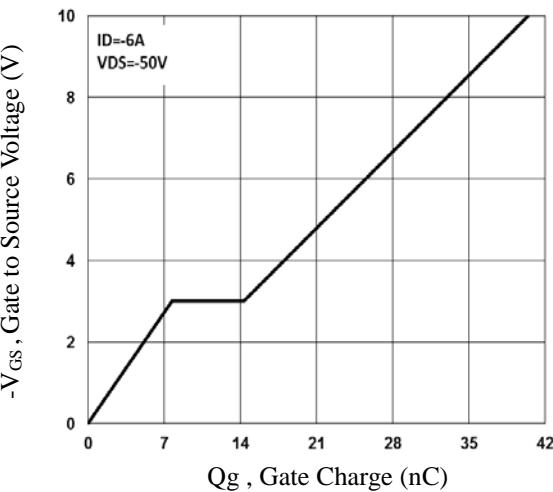


Fig.4 Gate Charge Waveform

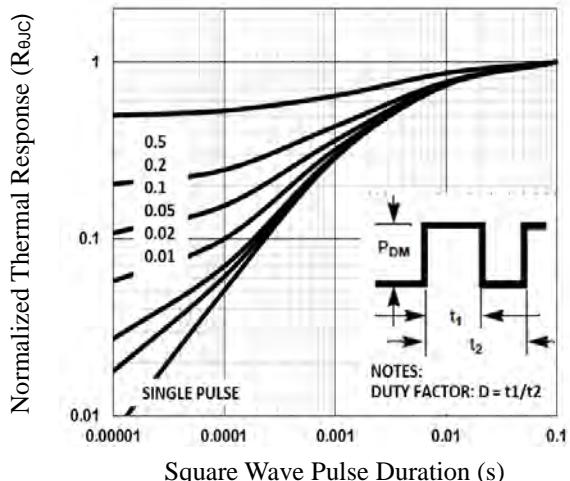


Fig.5 Normalized Transient Impedance

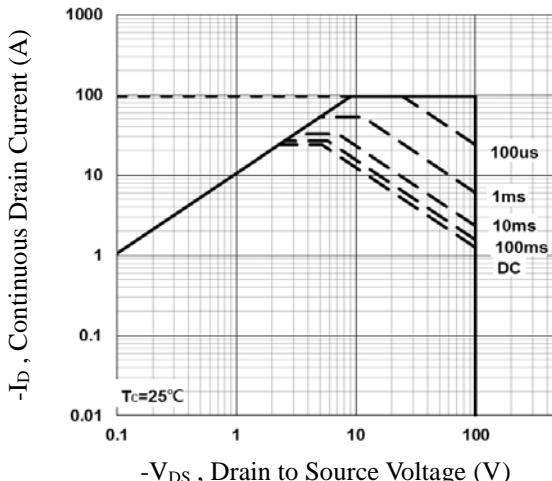


Fig.6 Maximum Safe Operation Area

-100V P-Channel MOSFETs

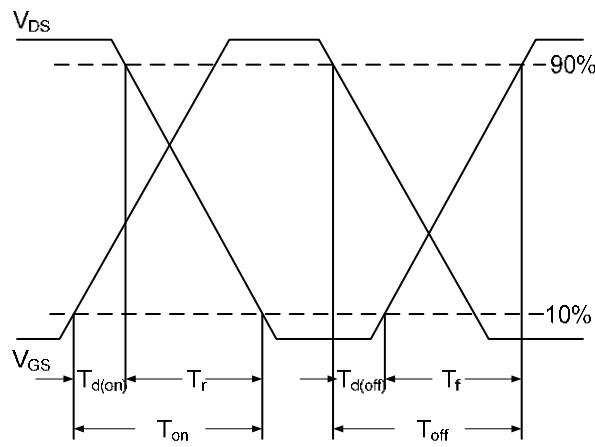


Fig.7 Switching Time Waveform

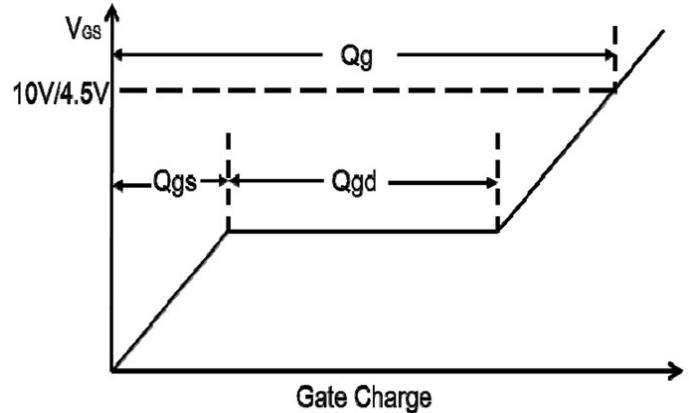
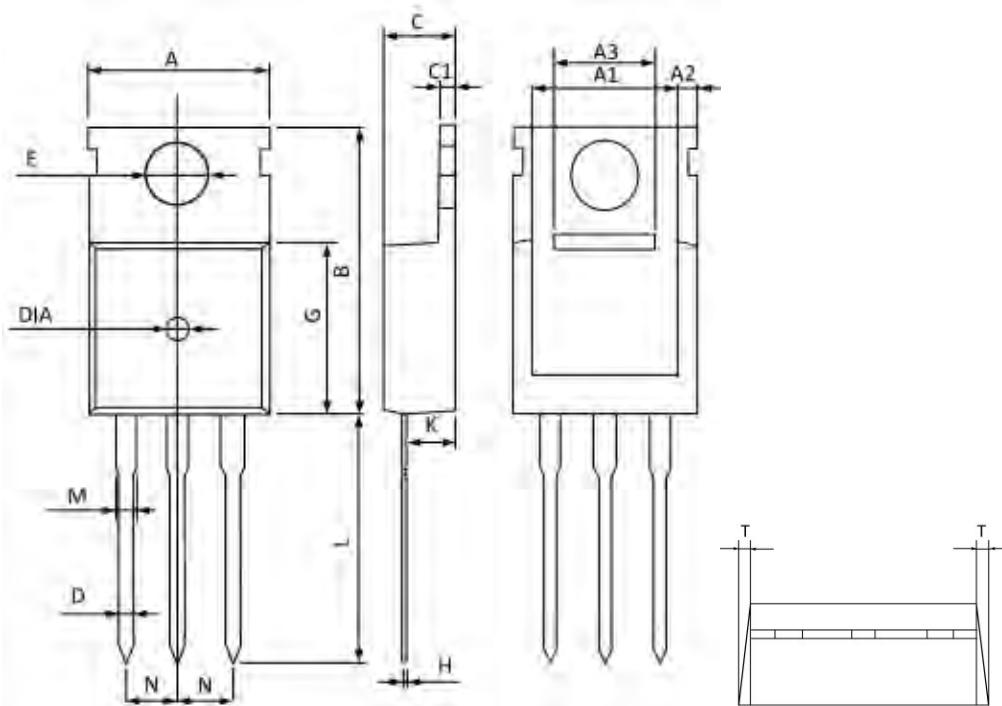


Fig.8 Gate Charge Waveform

-100V P-Channel MOSFETs

TO-220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.300	9.700	0.406	0.382
A1	8.840	8.440	0.348	0.332
A2	1.250	1.050	0.049	0.041
A3	5.300	5.100	0.209	0.201
B	16.200	15.400	0.638	0.606
C	4.680	4.280	0.184	0.169
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	3.800	3.400	0.150	0.134
G	9.300	8.700	0.366	0.343
H	0.600	0.400	0.024	0.016
K	2.700	2.100	0.106	0.083
L	13.600	12.800	0.535	0.504
M	1.500	1.100	0.059	0.043
N	2.590	2.490	0.102	0.098
T	W0.35		W0.014	
DIA	Φ1.5 TYP.	deep0.2 TYP.	Φ0.059 TYP.	deep0.008 TYP.